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Uwe F.W. Behringer
Jo Finders
Editors

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Foreword

On behalf of VDE/VDI-GMM, the sponsors, and the organizing committee, we would like to welcome you to the proceedings from the 31st European Mask and Lithography Conference, EMLC2015, at the Pullman Hotel in Eindhoven, Netherlands.

The conference has annually brought together scientists, researchers, engineers, and technologists from research institutes and companies from around the world to present innovations at the forefront of mask lithography and mask technology. The two-day conference was dedicated to the science, technology, engineering, and application of mask and lithography technologies and associated processes—giving an overview of the present status of mask and lithography technologies, while also providing future strategies where mask producers and users have the opportunity to become acquainted with new developments and results. This year's sessions included: Extension of Immersion Lithography, EUV Lithography, High NA EUV Lithography, EUV Mask Technology, Toward 7nm Technology, Mask Preparation and OPC, Mask Metrology, Mask Writing, and DSA .

Rob van Gijzel, mayor of the city of Eindhoven, was the welcome speaker.

Lucas van Grinsven, Head of Communication from ASML, was also a welcome speaker. His presentation was titled, "From Shed to Global Leader, ASML to the Brainport of the Netherlands."

Our first keynote speaker was Hans Meiling from ASML, who explained his statement: "EUV lithography into high volume manufacturing: "WHEN", not "IF."

Our second keynote speaker was Greg McIntyre from IMEC. His talk was titled, "Scaling trends and options: plenty of reason to be hopeful."

On Monday morning, Ingo Bork from Mentor Graphics Corporation presented the Best Paper from PMJ 2015 and the Best Poster from BACUS 2014.

On Monday late afternoon a poster session took place. This year some posters were organized by ASML, the co-partner of the EMLC2015. These selected posters were part of the ASML internal Technology Day on Wednesday, June 24.

Technical Exhibition

Parallel to the conference presentations, a technical exhibition took place on Monday and Tuesday where companies (mask suppliers, material suppliers, and equipment suppliers) exhibited their companies and products. To foster the

exchange between conference attendees and exhibitors, the exhibition area was also the place for all coffee and lunch breaks.

Uwe F.W. Behringer
EMLC2015 Conference Chair

Sponsors and Cooperating Partners

The 31st European Mask and Lithography Conference, EMLC2015, expresses its sincere appreciation to all the sponsors and cooperating partners listed below for their support.